

## Description

The XXW20P02S uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.



SOP-8

$V_{DS} = -20V$   $I_D = -20A$

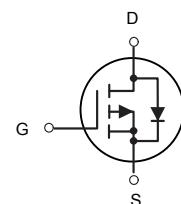
$R_{DS(ON)} < 19m\Omega$  @  $V_{GS}=10V$

## Application

Battery protection

Load switch

Uninterruptible power supply



P-Channel MOSFET

## Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	-20	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D@T_A=25^\circ C$	Drain Current <sup>3</sup> , $V_{GS}$ @ 10V	-20	A
$I_D@T_A=70^\circ C$	Drain Current <sup>3</sup> , $V_{GS}$ @ 10V	-16	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	-68	A
$P_D@T_A=25^\circ C$	Total Power Dissipation	18	W
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C
$R_{thj-a}$	Maximum Thermal Resistance, Junction-ambient <sup>3</sup>	75	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_{\text{D}}=-250\mu\text{A}$	-20	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_{\text{D}}=-1\text{mA}$	---	-0.012	---	$\text{V}^\circ\text{C}$
$R_{\text{DS}(\text{ON})}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-10\text{A}$	---	15	19	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}$ , $I_{\text{D}}=-8\text{A}$	---	19	23	
$V_{\text{GS}(\text{th})}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_{\text{D}}=-250\mu\text{A}$	-0.4	-0.7	-1.0	V
$\Delta V_{\text{GS}(\text{th})}$	$V_{\text{GS}(\text{th})}$ Temperature Coefficient		---	2.94	---	$\text{mV}^\circ\text{C}$
$I_{\text{DSS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\text{uA}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 12\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	$\pm 100$	$\text{nA}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=-5\text{V}$ , $I_{\text{D}}=-10\text{A}$	---	43	---	S
$Q_g$	Total Gate Charge (-4.5V)	$V_{\text{DS}}=-10\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $I_{\text{D}}=-10\text{A}$	---	35	---	$\text{nC}$
$Q_{\text{gs}}$	Gate-Source Charge		---	5.0	---	
$Q_{\text{gd}}$	Gate-Drain Charge		---	10	---	
$T_{\text{d}(\text{on})}$	Turn-On Delay Time		---	12.0	---	$\text{ns}$
$T_r$	Rise Time	$V_{\text{DD}}=-10\text{V}$ , $V_{\text{GS}}=-4.5\text{V}$ , $R_{\text{G}}=3.3\Omega$ , $I_{\text{D}}=-10\text{A}$	---	40.0	---	
$T_{\text{d}(\text{off})}$	Turn-Off Delay Time		---	30	---	
$T_f$	Fall Time		---	10	---	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=-15\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $f=1\text{MHz}$	---	2800	---	$\text{pF}$
$C_{\text{oss}}$	Output Capacitance		---	690	---	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	590	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current <sup>1,4</sup>	$V_G=V_D=0\text{V}$ , Force Current	---	---	-20.0	A
$I_{\text{SM}}$	Pulsed Source Current <sup>2,4</sup>		---	---	---	A
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	$V_{\text{GS}}=0\text{V}$ , $I_s=-1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	-1.2	V
$t_{\text{rr}}$	Reverse Recovery Time	$ I_F =-10\text{A}$ , $dI/dt=100\text{A}/\mu\text{s}$ ,	---	27	---	nS
$Q_{\text{rr}}$	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	17.8	---	$\text{nC}$

Note :

- 1.The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$  , duty cycle  $\leq 2\%$
- 3.The power dissipation is limited by  $150^\circ\text{C}$  junction temperature
- 4.The data is theoretically the same as  $I_D$  and  $I_{\text{DM}}$  , in real applications , should be limited by total power dissipation.

### Typical Characteristics

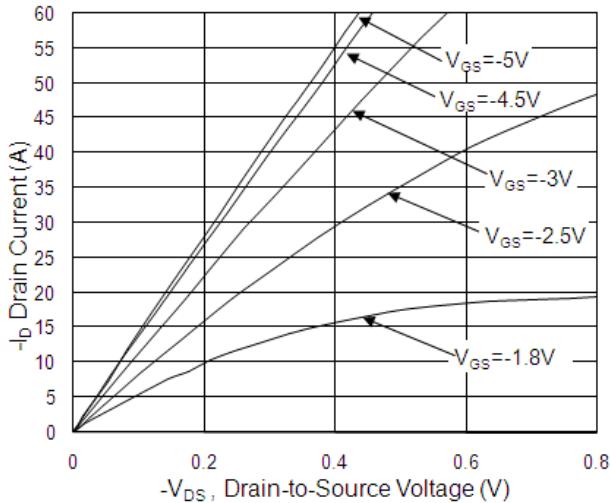


Fig.1 Typical Output Characteristics

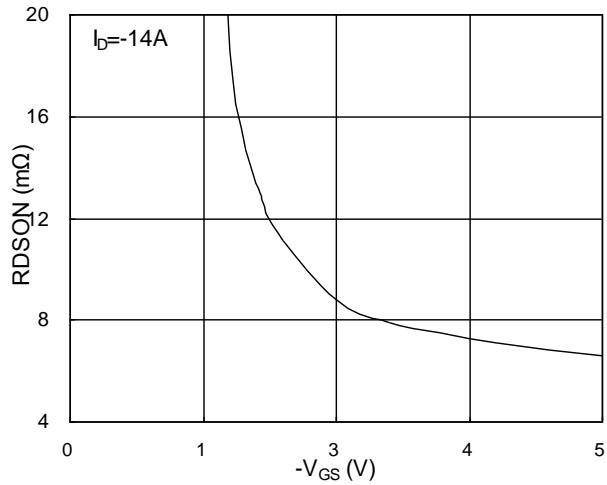


Fig.2 On-Resistance vs. G-S Voltage

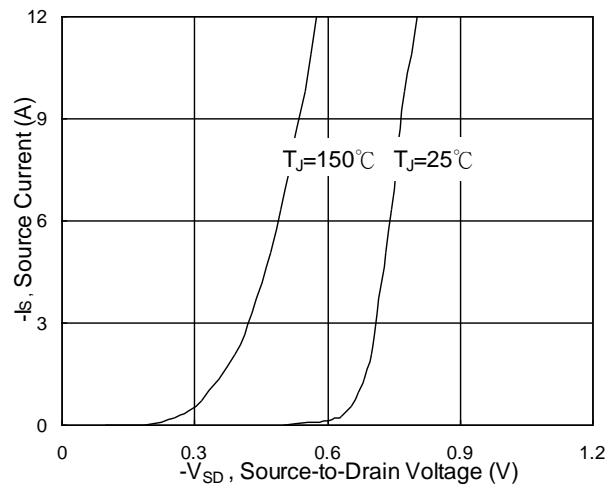


Fig.3 Forward Characteristics of Reverse

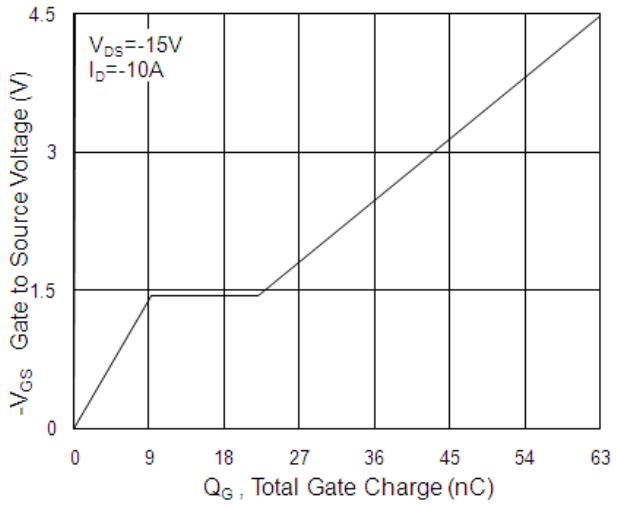


Fig.4 Gate-charge Characteristics

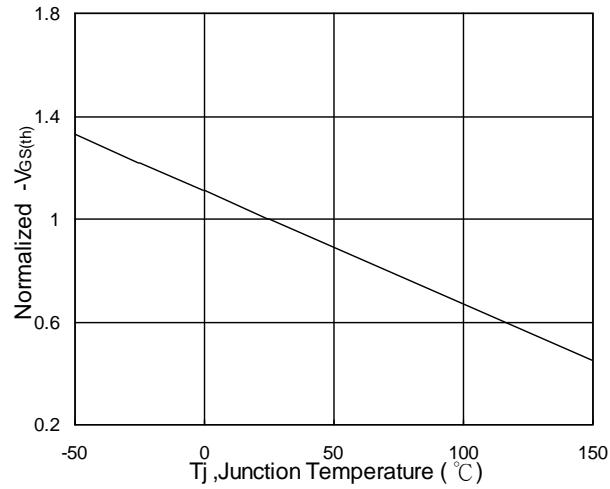


Fig.5 Normalized  $V_{GS(th)}$  vs.  $T_J$

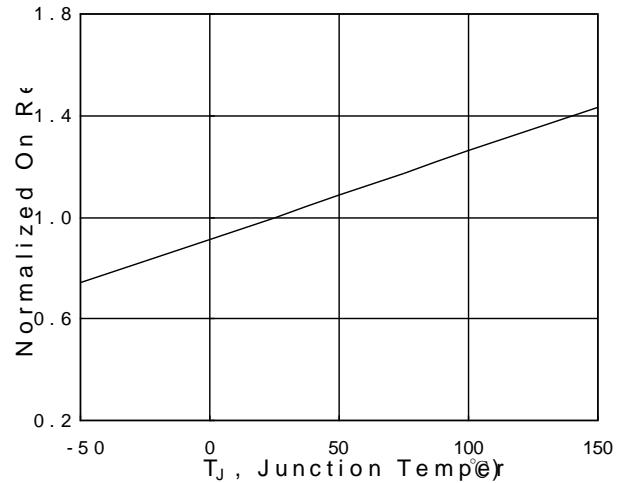
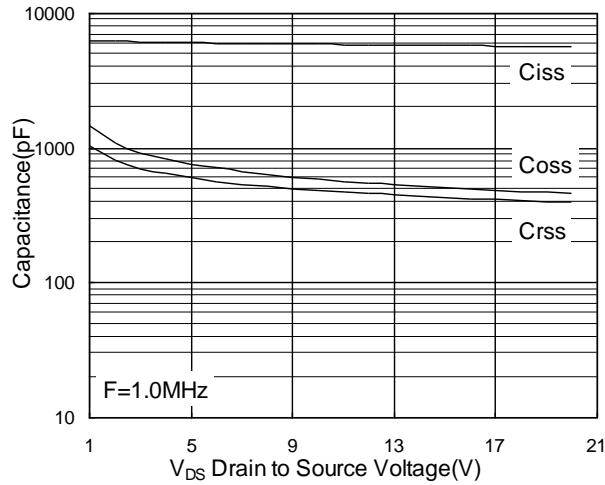
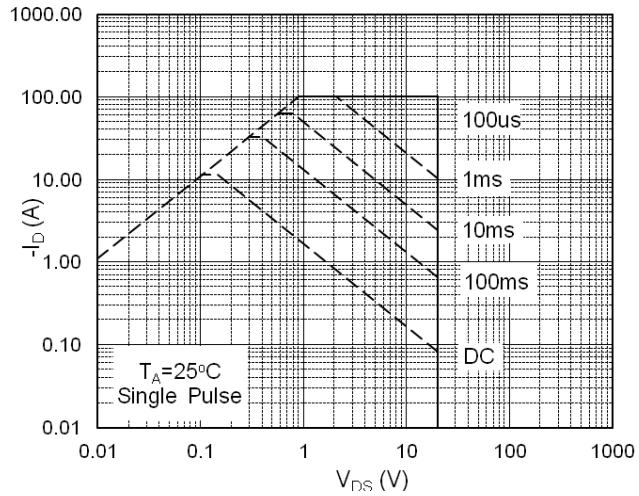
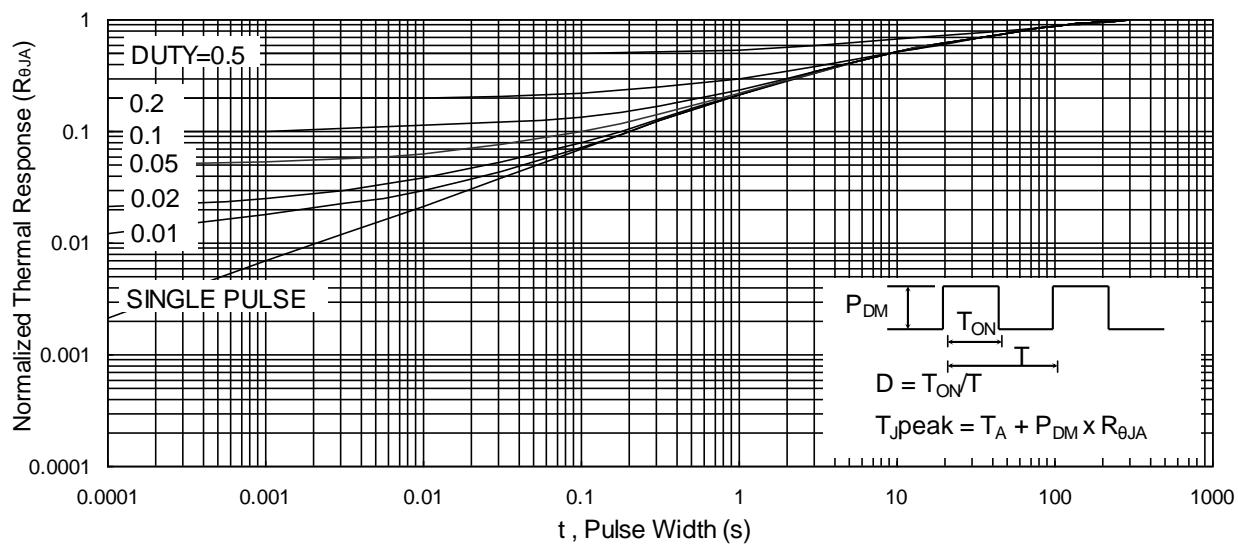
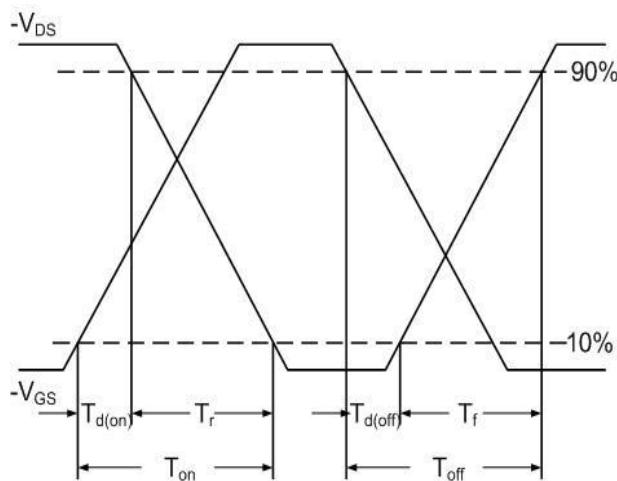
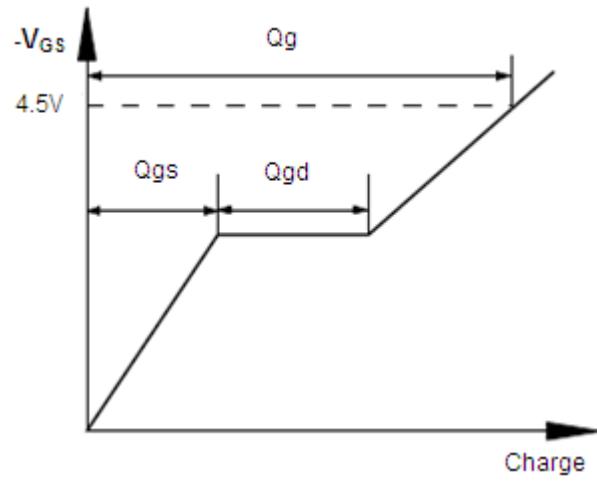
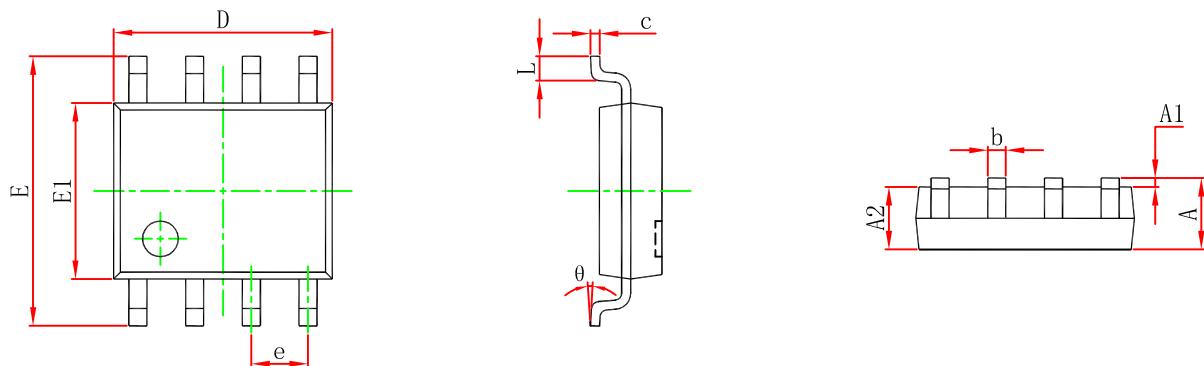


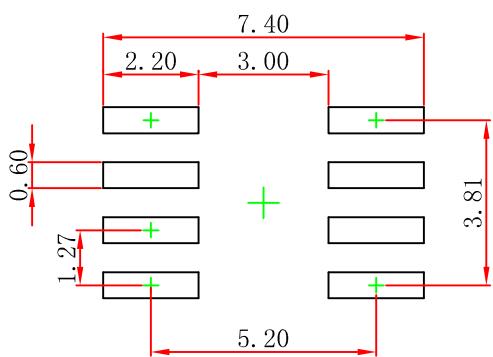
Fig.6 Normalized  $R_{DS(on)}$  vs.  $T_J$


**Fig.7 Capacitance**

**Fig.8 Safe Operating Area**

**Fig.9 Normalized Maximum Transient Thermal Impedance**

**Fig.10 Switching Time Waveform**

**Fig.11 Gate Charge Waveform**

### SOP-8 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
$\theta$	0°		8°	



Note:  
 1. Controlling dimension: in millimeters.  
 2. General tolerance:  $\pm 0.05$ mm.  
 3. The pad layout is for reference purposes only.